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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details

Product Status	Obsolete
Number of LABs/CLBs	150
Number of Logic Elements/Cells	1200
Total RAM Bits	9421
Number of I/O	211
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	256-LFBGA, CSPBGA
Supplier Device Package	256-CABGA (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lcmxo1200e-5b256c

Architecture Overview

The MachXO family architecture contains an array of logic blocks surrounded by Programmable I/O (PIO). Some devices in this family have sysCLOCK PLLs and blocks of sysMEM™ Embedded Block RAM (EBRs). Figures 2-1, 2-2, and 2-3 show the block diagrams of the various family members.

The logic blocks are arranged in a two-dimensional grid with rows and columns. The EBR blocks are arranged in a column to the left of the logic array. The PIO cells are located at the periphery of the device, arranged into Banks. The PIOs utilize a flexible I/O buffer referred to as a sysIO interface that supports operation with a variety of interface standards. The blocks are connected with many vertical and horizontal routing channel resources. The place and route software tool automatically allocates these routing resources.

There are two kinds of logic blocks, the Programmable Functional Unit (PFU) and the Programmable Functional unit without RAM (PFF). The PFU contains the building blocks for logic, arithmetic, RAM, ROM, and register functions. The PFF block contains building blocks for logic, arithmetic, ROM, and register functions. Both the PFU and PFF blocks are optimized for flexibility, allowing complex designs to be implemented quickly and effectively. Logic blocks are arranged in a two-dimensional array. Only one type of block is used per row.

In the MachXO family, the number of sysIO Banks varies by device. There are different types of I/O Buffers on different Banks. See the details in later sections of this document. The sysMEM EBRs are large, dedicated fast memory blocks; these blocks are found only in the larger devices. These blocks can be configured as RAM, ROM or FIFO. FIFO support includes dedicated FIFO pointer and flag “hard” control logic to minimize LUT use.

The MachXO registers in PFU and sysI/O can be configured to be SET or RESET. After power up and device is configured, the device enters into user mode with these registers SET/RESET according to the configuration setting, allowing device entering to a known state for predictable system function.

The MachXO architecture provides up to two sysCLOCK™ Phase Locked Loop (PLL) blocks on larger devices. These blocks are located at either end of the memory blocks. The PLLs have multiply, divide, and phase shifting capabilities that are used to manage the frequency and phase relationships of the clocks.

Every device in the family has a JTAG Port that supports programming and configuration of the device as well as access to the user logic. The MachXO devices are available for operation from 3.3V, 2.5V, 1.8V, and 1.2V power supplies, providing easy integration into the overall system.

The ispLEVER design tool takes the output of the synthesis tool and places and routes the design. Generally, the place and route tool is completely automatic, although an interactive routing editor is available to optimize the design.

Clock/Control Distribution Network

The MachXO family of devices provides global signals that are available to all PFUs. These signals consist of four primary clocks and four secondary clocks. Primary clock signals are generated from four 16:1 muxes as shown in Figure 2-7 and Figure 2-8. The available clock sources for the MachXO256 and MachXO640 devices are four dual function clock pins and 12 internal routing signals. The available clock sources for the MachXO1200 and MachXO2280 devices are four dual function clock pins, up to nine internal routing signals and up to six PLL outputs.

Figure 2-7. Primary Clocks for MachXO256 and MachXO640 Devices

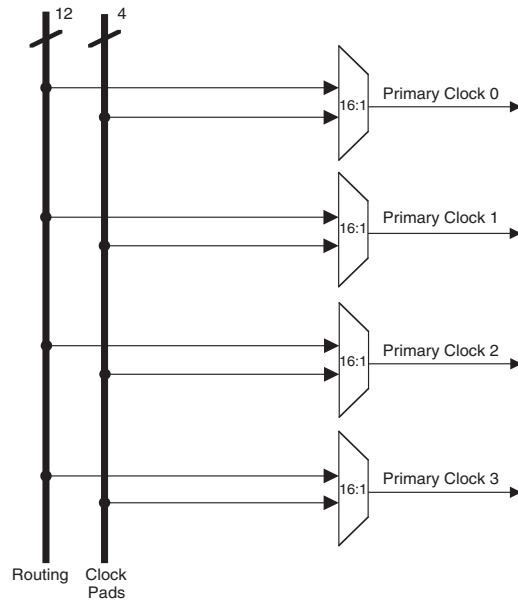
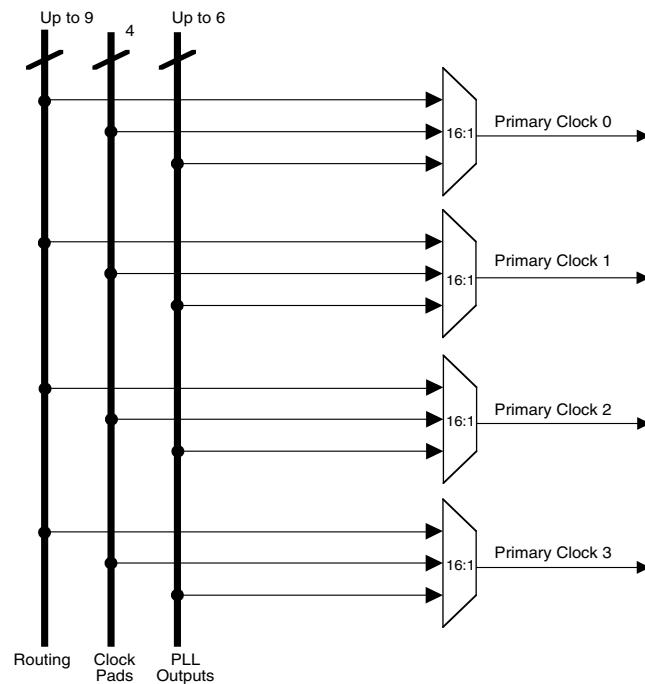


Figure 2-8. Primary Clocks for MachXO1200 and MachXO2280 Devices



Four secondary clocks are generated from four 16:1 muxes as shown in Figure 2-9. Four of the secondary clock sources come from dual function clock pins and 12 come from internal routing.

Figure 2-9. Secondary Clocks for MachXO Devices

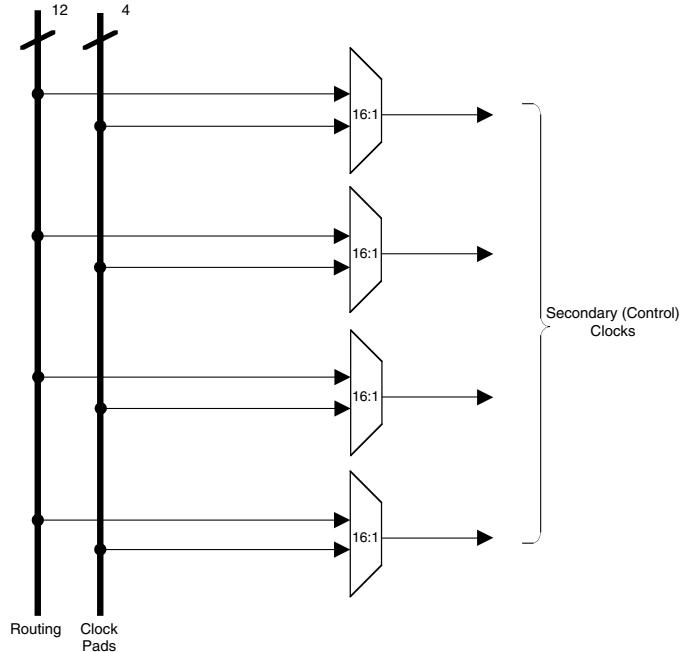
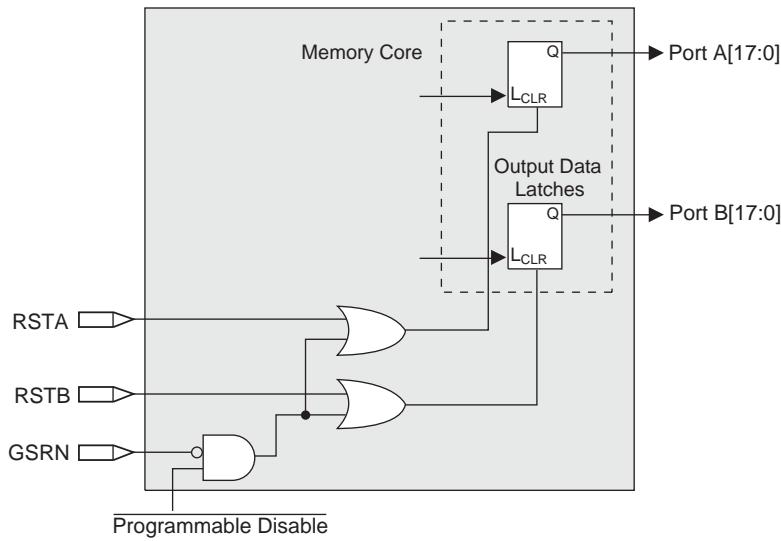


Figure 2-13. Memory Core Reset

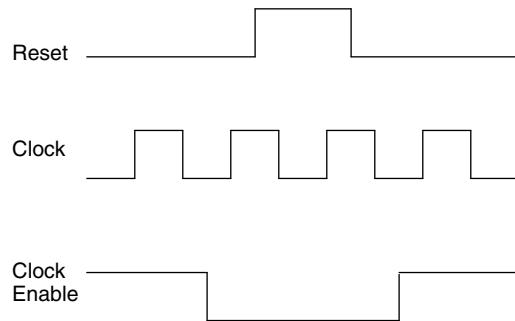


For further information on the sysMEM EBR block, see the details of additional technical documentation at the end of this data sheet.

EGR Asynchronous Reset

EGR asynchronous reset or GSR (if used) can only be applied if all clock enables are low for a clock cycle before the reset is applied and released a clock cycle after the reset is released, as shown in Figure 2-14. The GSR input to the EGR is always asynchronous.

Figure 2-14. EGR Asynchronous Reset (Including GSR) Timing Diagram



If all clock enables remain enabled, the EGR asynchronous reset or GSR may only be applied and released after the EGR read and write clock inputs are in a steady state condition for a minimum of $1/f_{MAX}$ (EGR clock). The reset release must adhere to the EGR synchronous reset setup time before the next active read or write clock edge.

If an EGR is pre-loaded during configuration, the GSR input must be disabled or the release of the GSR during device Wake Up must occur before the release of the device I/Os becoming active.

These instructions apply to all EGR RAM, ROM and FIFO implementations. For the EGR FIFO mode, the GSR signal is always enabled and the WE and RE signals act like the clock enable signals in Figure 2-14. The reset timing rules apply to the RPReset input vs the RE input and the RST input vs. the WE and RE inputs. Both RST and RPReset are always asynchronous EGR inputs.

Note that there are no reset restrictions if the EGR synchronous reset is used and the EGR GSR input is disabled

Table 2-10. Supported Output Standards

Output Standard	Drive	V_{CCIO} (Typ.)
Single-ended Interfaces		
LV TTL	4mA, 8mA, 12mA, 16mA	3.3
LVC MOS33	4mA, 8mA, 12mA, 14mA	3.3
LVC MOS25	4mA, 8mA, 12mA, 14mA	2.5
LVC MOS18	4mA, 8mA, 12mA, 14mA	1.8
LVC MOS15	4mA, 8mA	1.5
LVC MOS12	2mA, 6mA	1.2
LVC MOS33, Open Drain	4mA, 8mA, 12mA, 14mA	—
LVC MOS25, Open Drain	4mA, 8mA, 12mA, 14mA	—
LVC MOS18, Open Drain	4mA, 8mA, 12mA, 14mA	—
LVC MOS15, Open Drain	4mA, 8mA	—
LVC MOS12, Open Drain	2mA, 6mA	—
PCI33 ³	N/A	3.3
Differential Interfaces		
LVDS ^{1,2}	N/A	2.5
BLVDS, RS DS ²	N/A	2.5
LVPECL ²	N/A	3.3

1. MachXO1200 and MachXO2280 devices have dedicated LVDS buffers.

2. These interfaces can be emulated with external resistors in all devices.

3. Top Banks of MachXO1200 and MachXO2280 devices only.

sysIO Buffer Banks

The number of Banks vary between the devices of this family. Eight Banks surround the two larger devices, the MachXO1200 and MachXO2280 (two Banks per side). The MachXO640 has four Banks (one Bank per side). The smallest member of this family, the MachXO256, has only two Banks.

Each sysIO buffer Bank is capable of supporting multiple I/O standards. Each Bank has its own I/O supply voltage (V_{CCIO}) which allows it to be completely independent from the other Banks. Figure 2-18, Figure 2-18, Figure 2-20 and Figure 2-21 shows the sysIO Banks and their associated supplies for all devices.

For further information on LVPECL, BLVDS and other differential interfaces please see details of additional technical documentation at the end of the data sheet.

RSDS

The MachXO family supports the differential RSDS standard. The output standard is emulated using complementary LVCMS outputs in conjunction with a parallel resistor across the driver outputs on all the devices. The RSDS input standard is supported by the LVDS differential input buffer on certain devices. The scheme shown in Figure 3-4 is one possible solution for RSDS standard implementation. Use LVDS25E mode with suggested resistors for RSDS operation. Resistor values in Figure 3-4 are industry standard values for 1% resistors.

Figure 3-4. RSDS (Reduced Swing Differential Standard)

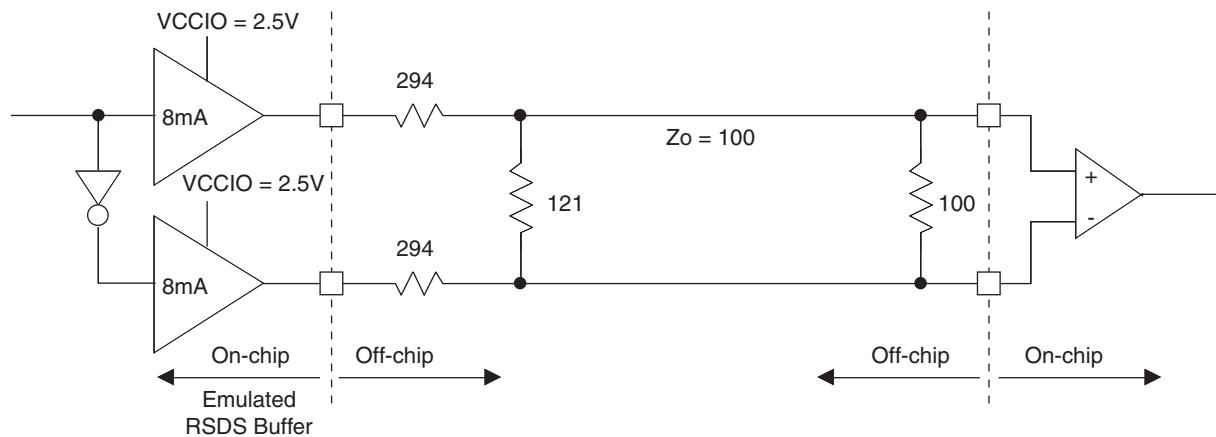


Table 3-4. RSDS DC Conditions

Parameter	Description	Typical	Units
Z_{OUT}	Output impedance	20	Ohms
R_S	Driver series resistor	294	Ohms
R_P	Driver parallel resistor	121	Ohms
R_T	Receiver termination	100	Ohms
V_{OH}	Output high voltage	1.35	V
V_{OL}	Output low voltage	1.15	V
V_{OD}	Output differential voltage	0.20	V
V_{CM}	Output common mode voltage	1.25	V
Z_{BACK}	Back impedance	101.5	Ohms
I_{DC}	DC output current	3.66	mA

Date	Version	Section	Change Summary
April 2006 (cont.)	02.0 (cont.)	Architecture (cont.)	<p>"Top View of the MachXO1200 Device" figure updated.</p> <p>"Top View of the MachXO640 Device" figure updated.</p> <p>"Top View of the MachXO256 Device" figure updated.</p> <p>"Slice Diagram" figure updated.</p> <p>Slice Signal Descriptions table updated.</p> <p>Routing section updated.</p> <p>sysCLOCK Phase Locked Loops (PLLs) section updated.</p> <p>PLL Diagram updated.</p> <p>PLL Signal Descriptions table updated.</p> <p>sysMEM Memory section has been updated.</p> <p>PIO Groups section has been updated.</p> <p>PIO section has been updated.</p> <p>MachXO PIO Block Diagram updated.</p> <p>Supported Input Standards table updated.</p> <p>MachXO Configuration and Programming diagram updated.</p>
		DC and Switching Characteristics	<p>Recommended Operating Conditions table - footnotes updated.</p> <p>MachXO256 and MachXO640 Hot Socketing Specifications - footnotes updated.</p> <p>Added MachXO1200 and MachXO2280 Hot Socketing Specifications table.</p> <p>DC Electrical Characteristics, footnotes have been updated.</p> <p>Supply Current (Sleep Mode) table has been updated, removed "4W" references. Footnotes have been updated.</p> <p>Supply Current (Standby) table and associated footnotes updated.</p> <p>Initialization Supply Current table and footnotes updated.</p> <p>Programming and Erase Flash Supply Current table and associated footnotes have been updated.</p> <p>Register-to-Register Performance table updated (rev. A 0.19).</p> <p>MachXO External Switching Characteristics updated (rev. A 0.19).</p> <p>MachXO Internal Timing Parameters updated (rev. A 0.19).</p> <p>MachXO Family Timing Adders updated (rev. A 0.19).</p> <p>sysCLOCK Timing updated (rev. A 0.19).</p> <p>MachXO "C" Sleep Mode Timing updated (A 0.19).</p> <p>JTAG Port Timing Specification updated (rev. A 0.19).</p> <p>Test Fixture Required Components table updated.</p>
		Pinout Information	<p>Signal Descriptions have been updated.</p> <p>Pin Information Summary has been updated. Footnote has been added.</p> <p>Power Supply and NC Connection table has been updated.</p> <p>Logic Signal Connections have been updated (PCLKTx_x --> PCLKx_x)</p>
		Ordering Information	<p>Removed "4W" references.</p> <p>Added 256-ftBGA Ordering Part Numbers for MachXO640.</p>
May 2006	02.1	Pinout Information	<p>Removed [LOC][0]_PLL_RST from Signal Description table.</p> <p>PCLK footnote has been added to all appropriate pins.</p>
August 2006	02.2	Multiple	Removed 256 fpBGA information for MachXO640.